



RECOMMENDED PCB LAYOUT

HOW TO ORDER:

W 3 0 0 - 0 7 1 5 - 2 5 X 0 - Z

SELECTIVE CONTACT PLATING:

- 1 - 0.127 μm [5 μm] SELECTIVE GOLD PLATING
- 2 - 0.254 μm [10 μm] SELECTIVE GOLD PLATING
- 3 - 0.381 μm [15 μm] SELECTIVE GOLD PLATING
- 4 - 0.508 μm [20 μm] SELECTIVE GOLD PLATING
- 5 - 0.762 μm [30 μm] SELECTIVE GOLD PLATING

PACKAGING:

0 - Tube

RoHS COMPLIANT

ELETRICAL:

CURRENT RATING: 1.5 A
 VOLTAGE RATING: 12 VAC max.
 CONTACT RESISTANCE: 30 m Ω max.
 DIELECTRIC WITHSTANDING VOLTAGE: 500 VAC for 1 min (sea level)
 INSULATION RESISTANCE: 1000 M Ω min.

MATERIAL:

INSULATOR: Thermoplastic - 30% Glass Fiber Reinforced UL94 V-0
 CONTACTS: Copper Alloy
 CONTACT PLATING: Selective Gold Plated on Contact Area Over 50 μm Min. NI Under Plated
 100 μm Min. Tin Plating on Solder Tails
 BOARDLOCKS: Brass

ENVIRONMENTAL:

TEMPERATURE : -40°C to 105°C

Rev	Drawn	Checked	Approved	Date
0	B.S.	S.M.	S.M.	07/09/14
A	B.S.	S.M.	S.M.	07/16/14

SMP TECHNOLOGY, INC.

SATA, 7 Pin, Male, Vertical, Offset Mounting, Surface Mount;

Stamped Flat Boardlock

TOL. DEC. .X +/- 0.3 .XX +/- 0.2 .XXX +/- 0.1 ANGLE +/-5° UNIT: mm

P/N: W300-0715-25X0-Z